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ThinFlex H-0505RS-C Adhesiveless Copper Clad Laminate

IPC Designation IPC-4204/11

ThinFlex-H is an Adhesiveless metal clad polyimide film, furnished in the form of roll laminate with RA or ED copper on one sides. ThinFlex-H adhessiveless composites are designed for a wide variety of flexible printed circuits (FPC) applications which require advanced material performance, temperature resistance, fine pitch, and high reliablity.

1. Product Characteristics:

- * Excellent dimensional stability
- * Excellent flexibility
- * Excellent anti-flammability (Flame class UL 94VTM-0 VL file No.E219724)
- * Excellent line etch ability
- * Low moisture absorption
- * Excellent chemical resistance
- * Excellent thermal, mechanical and electrical properties
- * Products can meet the environmental requirements of Topflex RoHs/Reach....

2. Specifications:

<u> H - 05 05 R S - C </u>								
Product	Thickness of PI	Thickness of Cu	Type of Cu	Structure	Code of Product company			
H:2-FCCL	05: 0.5mil	05 : 1/2 oz	R : RA Cu	S: Single	Fukuda			
Supply Size	W: $250/500 \pm 1$ mm; L: $100 + 2/-0$ m (Roll type) splice ≤ 3							

*Other thicknesses and dimensions are available on customers' demand.





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3. Construction:	1	/2oz TNBG Coppe			
4. Properties:		0.5mil Polyimide	IPC Designation IPC-42	04/11	
Test item		Unit	H-0505RS-C	Test Method	
Peel Strength					
As Received		Kgf/cm	≥ 0.7	IPC-TM650 2.4.9	
Solder Float	Kgf/cm	≥ 0.7	IPC-TM650 2.4.9		
After Temp. Cycling	Kgf/cm	≥ 0.7	IPC-TM650 2.4.9		
Chemical Resistance	Kgf/cm	≥ 0.7	IPC-TM650 2.3.2		
Tensile Strength (Base Film)	Kg/mm ²	>15	IPC-TM-650 2.4.19		
Elongation (Base Film)	%	>10	IPC-TM-650 2.4.19		
Tensile Modulus (Base Film)	Kg/mm ²	600	ASTM D882		
Initial Tear Strength (Base F	g	420	IPC-TM-650 2.4.16		
Propagation Tear Strength (H	g	10	IPC-TM-650 2.4.17.1		
Flexural Endurance, MIT					
M.D.	Cycles	≥900	JIS-C 6471, 0.8mmR, 0.5kg		
T.D.	Cycles	≥900	JIS-C 6471, 0.8mmR, 0.5kg		
Electrical Properties					
Surface Resistance	Ω	~1011	IPC-TM650 2.5.17		
Volume Resistance		Ω-cm	~10 ¹²	IPC-TM650 2.5.17	
Insulation Resistance		Ω	~10 ¹⁰	IPC-TM650 2.6.3.2	
Dielectric Strength		kV/mil	5.0	ASTM-D149	
Dielectric Constant		-	3.6	IPC-TM650 2.5.5.3	
Dissipation factor		-	0.01	IPC-TM650 2.5.5.3	
Physical and Thermal Proper	rties				
	M.D.	%	-0.1~0.1	IPC-TM650 2.2.4C	
Dimensional Stability	T.D.	%	-0.1~0.1	IPC-TM650 2.2.4C	
CTE		ppm/°C	26	ThinFlex	
T_{g}		°C	327	ThinFlex	
Solder Float	10sec at 288°C (550⁰F) -	Pass	IPC-TM650 2.4.13	
Moisture Absorption Test		%	1.1	IPC-TM650 2.6.2	
Chemical Resistance-single		-	Pass	IPC-TM650 2.3.2	
Thickness tolerance	um	31±10%	ThinFlex		
UL Flame Class		-	94VTM-0	UL	

* Above data are typical values, and are not guaranteed values.

Technical Data Sheet: 2018/03



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5. Storage:

ThinFlex-H will meet its shelf-life for at least 12 months from product date when stored in the original packaging at temperatures of $20 \pm 10^{\circ}$ C and $50\pm 20\%$ humidity. The products do not need refrigeration and should not be frozen.

Note: The information and data contained in this technical literature is believed to be accurate and is offered in good faith for the benefit of the user. The user should make his own tests to verify the suitability of this product for any application before its use. All data are typical values only and subject to change without notice.

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